

DESCRIPTION

The MXD30N50 uses advanced trench technology to provide excellent $R_{DS(ON)}$ and low gate charge. It can be used in a wide variety of applications.

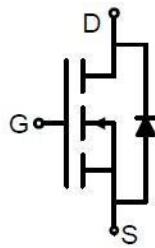
GENERAL FEATURES

- $V_{DS}=30V$, $I_D=50A$
- $R_{DS(ON)}(\text{Typ.})=11\text{m}\Omega$ @ $V_{GS}=4.5V$
- $R_{DS(ON)}(\text{Typ.})=7\text{m}\Omega$ @ $V_{GS}=10V$
- High Power and current handing capability
- Lead free product is acquired
- Surface Mount Package

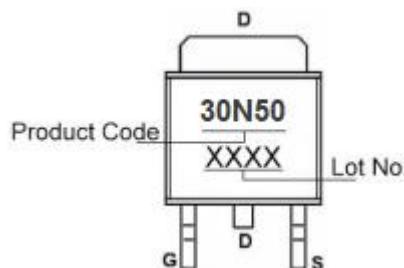
APPLICATION

- Battery management
- Motor controller and driver
- PWM applications
- Load switch

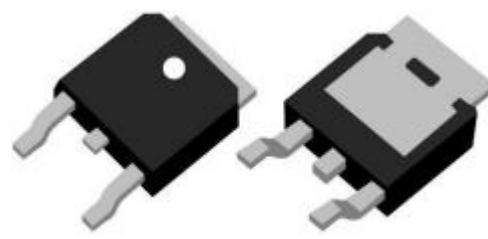
PINOUT



Schematic diagram



Marking and pin Assignment



TO-252-2L top & bottom view

ORDERING INFORMATION

| Part Number | Storage Temperature | Package | Devices Per Reel |
|-------------|---------------------|-----------|------------------|
| MX30N50 | -55°C to 150°C | TO-252-2L | - |

ABSOLUTE MAXIMUM RATINGS ($T_C=25^\circ\text{C}$ unless otherwise noted)

| Parameter | Symbol | Limit | Unit |
|-----------------------------------------------------|----------------|------------|------|
| Drain-Source Voltage | V_{DS} | 30 | V |
| Gate-Source Voltage | V_{GS} | ± 20 | V |
| Drain Current-Continuous | I_D | 50 | A |
| Drain Current-Continuous($T_C=100^\circ\text{C}$) | I_D | 35 | A |
| Pulsed Drain Current ^(Note1) | I_{DM} | 140 | A |
| Maximum Power Dissipation | P_D | 37.5 | W |
| Operating Junction and Storage Temperature Range | T_J, T_{STG} | -55 to 150 | °C |

THERMAL RESISTANCE

| | | | |
|---------------------------------------------------------|-----------------|---|------|
| Thermal Resistance, Junction-to-Case ^(Note2) | $R_{\theta JC}$ | 4 | °C/W |
|---------------------------------------------------------|-----------------|---|------|

Note 1. Repetitive Rating: Pulse width limited by maximum junction temperature.

Note 2. Surface Mounted on FR4 Board, $t \leq 10$ sec.


ELECTRICAL CHARACTERISTICS($T_A=25^\circ\text{C}$ unless otherwise noted)

| Parameter | Symbol | Conditions | Min | Typ | Max | Unit |
|-----------|--------|------------|-----|-----|-----|------|
|-----------|--------|------------|-----|-----|-----|------|

Off Characteristics

| | | | | | | |
|---------------------------------|--------------------------|---------------------------------------------------------|----|---|-----------|---------------|
| Drain-Source Breakdown Voltage | BV_{DSS} | $V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$ | 30 | - | - | V |
| Zero Gate Voltage Drain Current | I_{DSS} | $V_{\text{DS}}=30\text{V}, V_{\text{GS}}=0\text{V}$ | - | - | 1 | μA |
| Gate-Body Leakage Current | I_{GSS} | $V_{\text{GS}}=\pm 20\text{V}, V_{\text{DS}}=0\text{V}$ | - | - | ± 100 | nA |

On Characteristics^(Note2)

| | | | | | | |
|----------------------------------|----------------------------|------------------------------------------------------------|-----|-----|-----|------------------|
| Gate Threshold Voltage | $V_{\text{GS}(\text{th})}$ | $V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$ | 1.0 | 1.5 | 2.2 | V |
| Drain-Source On-State Resistance | $R_{\text{DS}(\text{ON})}$ | $V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=13\text{A}$ | - | 11 | 14 | $\text{m}\Omega$ |
| | | $V_{\text{GS}}=10\text{V}, I_{\text{D}}=16\text{A}$ | - | 7 | 8.5 | $\text{m}\Omega$ |
| Forward Transconductance | g_{FS} | $V_{\text{DS}}=5\text{V}, I_{\text{D}}=20\text{A}$ | - | 42 | - | S |

Dynamic Characteristics^(Note3)

| | | | | | | |
|------------------------------|------------------|----------------------------------------------------------------------|---|------|---|----------|
| Input Capacitance | C_{iss} | $V_{\text{DS}}=15\text{V}, V_{\text{GS}}=0\text{V}, F=1.0\text{MHz}$ | - | 1300 | - | pF |
| Output Capacitance | C_{oss} | | - | 140 | - | pF |
| Reverse Transfer Capacitance | C_{rss} | | - | 130 | - | pF |
| Gate Resistance | R_g | $V_{\text{DS}}=0\text{V}, V_{\text{GS}}=0\text{V}, F=1.0\text{MHz}$ | - | 2.2 | - | Ω |

Switching Characteristics

| | | | | | | |
|---------------------|----------------------------|--------------------------------------------------------------------------------------------------------|---|-----|---|----|
| Turn-on Delay Time | $t_{\text{d}(\text{on})}$ | $V_{\text{DD}}=15\text{V}, I_{\text{D}}=2\text{A}, R_L=1\Omega, V_{\text{GS}}=10\text{V}, R_G=3\Omega$ | - | 7.2 | - | nS |
| Turn-on Rise Time | t_r | | - | 12 | - | nS |
| Turn-Off Delay Time | $t_{\text{d}(\text{off})}$ | | - | 23 | - | nS |
| Turn-Off Fall Time | t_f | | - | 8 | - | nS |
| Total Gate Charge | Q_g | $V_{\text{DS}}=15\text{V}, I_{\text{D}}=25\text{A}, V_{\text{GS}}=10\text{V}$ | - | 28 | - | nC |
| Gate-Source Charge | Q_{gs} | | - | 3.5 | - | nC |
| Gate-Drain Charge | Q_{gd} | | - | 7 | - | nC |

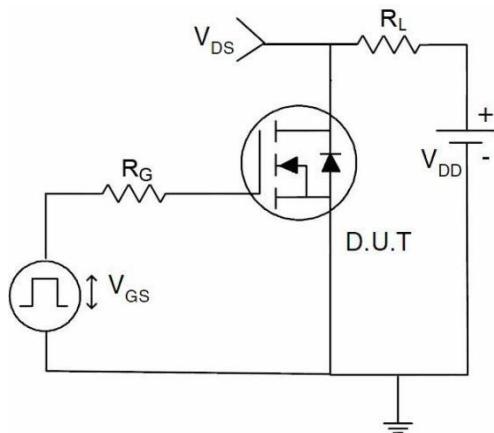
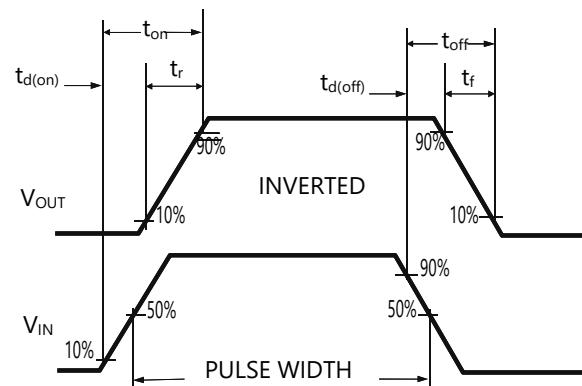
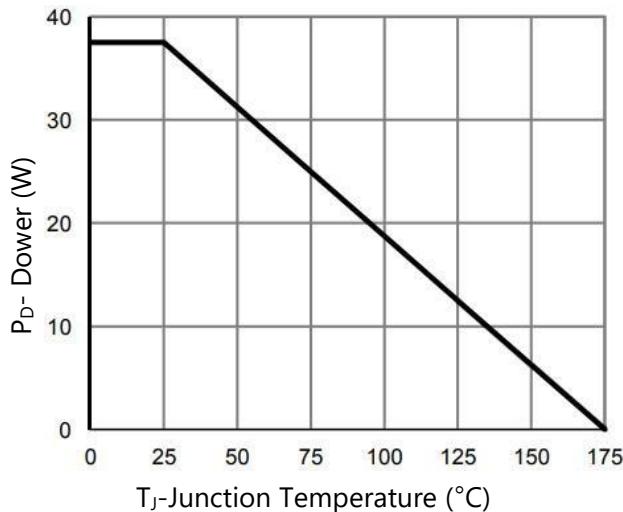
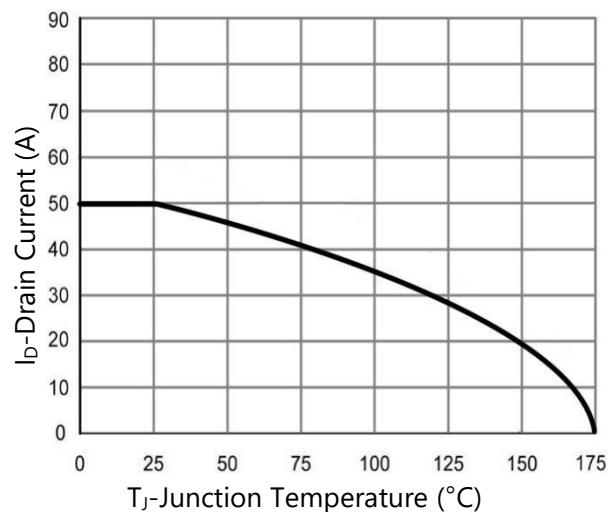
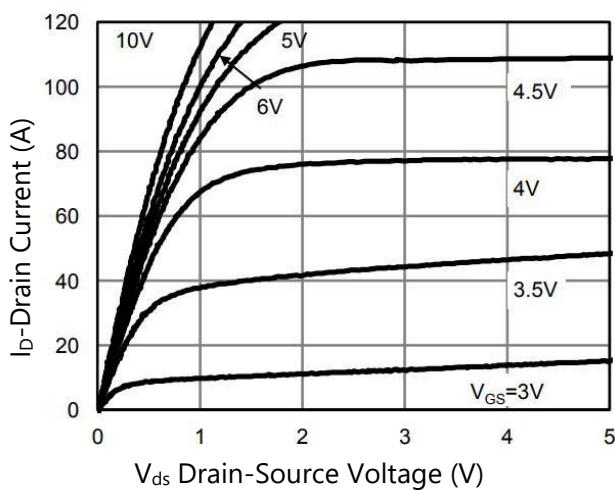
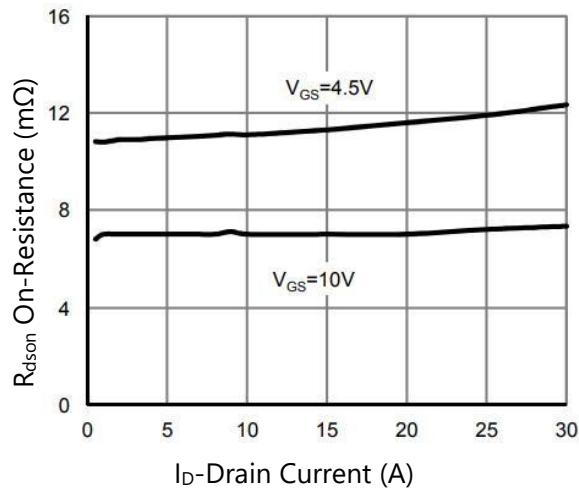
Drain-Source Diode Characteristics

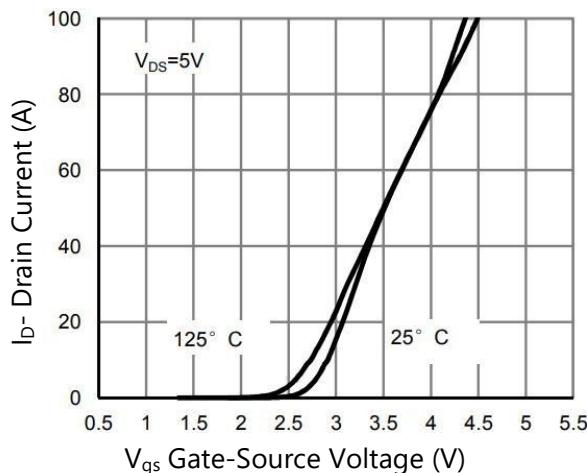
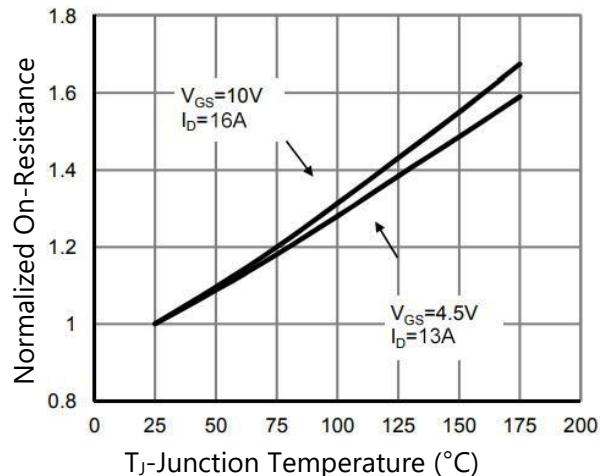
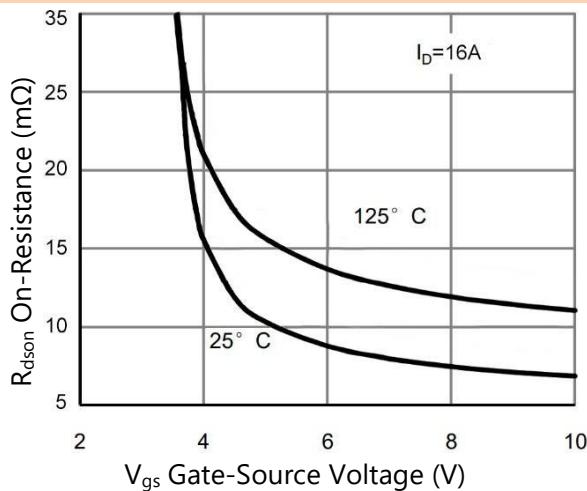
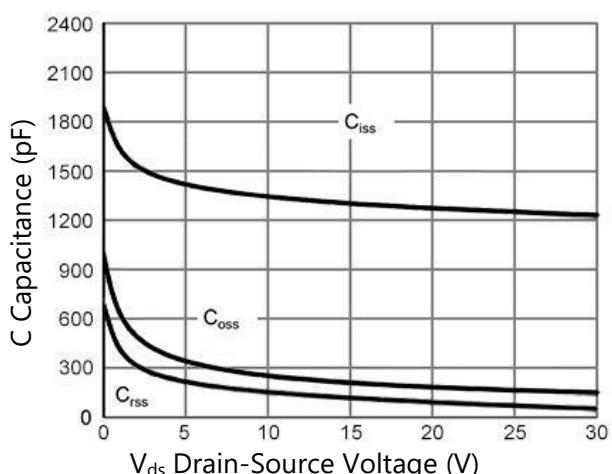
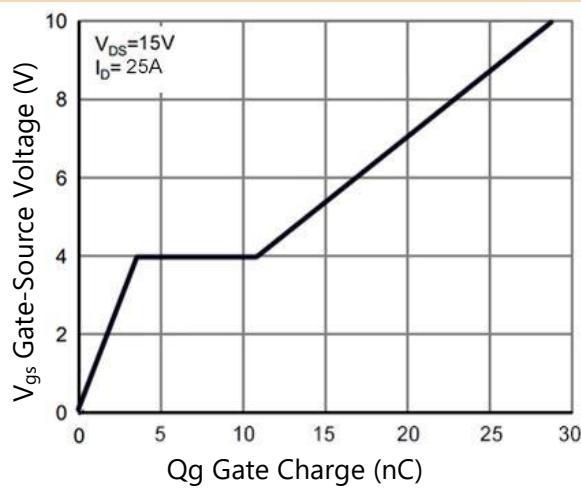
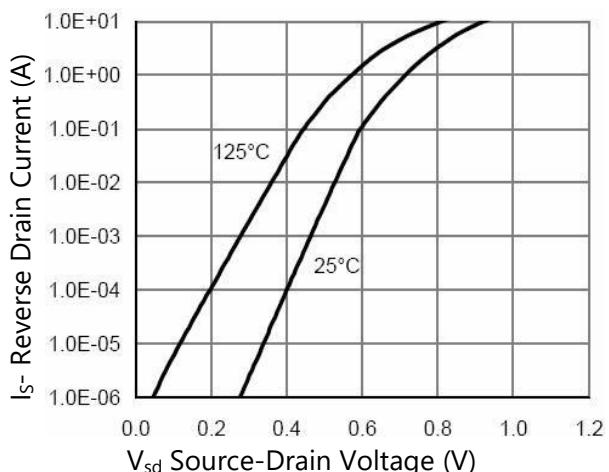
| | | | | | | |
|------------------------------------------|-----------------|---------------------------------------------------|---|---|-----|---|
| Diode Forward Voltage ^(Note2) | V_{SD} | $V_{\text{GS}}=0\text{V}, I_{\text{S}}=1\text{A}$ | - | - | 1.2 | V |
| Diode Forward Current ^(Note1) | I_{S} | | - | - | 40 | A |

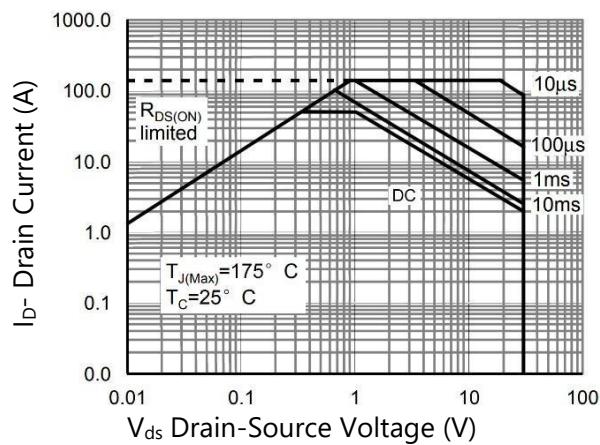
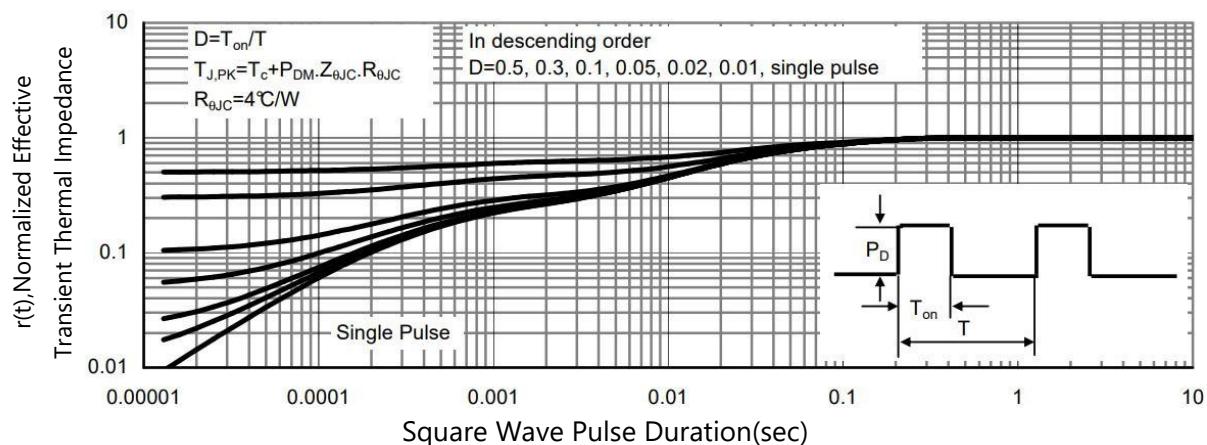
Note 1. Surface Mounted on FR4 Board, $t \leq 10$ sec.

Note 2. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$.

Note 3. Guaranteed by design, not subject to product.

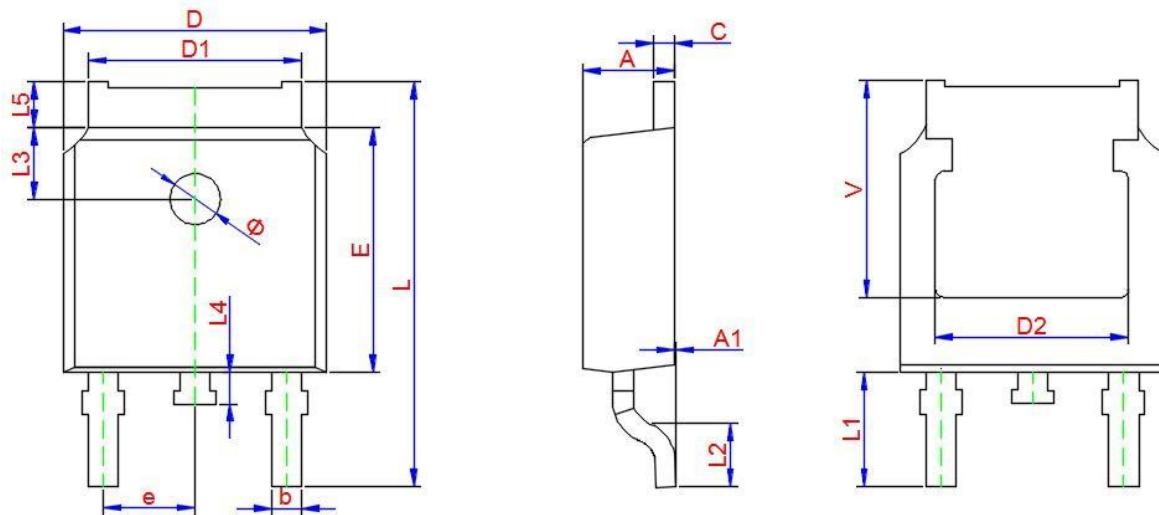

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS
Figure 1. Switching Test Circuit

Figure 2. Switching Waveform

Figure 3. Power Dissipation

Figure 4. Drain Current

Figure 5. Output Characteristics

Figure 6. R_{dson} vs Drain Current



TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS
Figure 7. Transfer Characteristics

Figure 8. $R_{ds(on)}$ vs Junction Temperature

Figure 9. $R_{ds(on)}$ vs V_{gs}

Figure 10. Capacitance vs V_{DS}

Figure 11. Gate Charge

Figure 12. Source- Drain Diode Forward



TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS
Figure 13. Safe Operation Area

Figure 14. Normalized Maximum Transient Thermal Impedance


PACKAGE INFORMATION

TO-252-2L



| Symbol | Dimensions in Millimeters | | |
|--------|---------------------------|--------|--------|
| | Min. | Typ. | Max. |
| A | 2.200 | 2.300 | 2.400 |
| A1 | 0.000 | - | 0.127 |
| D | 6.500 | 6.600 | 6.700 |
| D1 | 5.100 | 5.330 | 5.460 |
| C | 0.450 | 0.500 | 0.600 |
| D2 | 4.830 TYP. | | |
| E | 6.000 | 6.100 | 6.200 |
| e | 2.186 | 2.286 | 2.386 |
| L | 9.800 | 10.100 | 10.400 |
| L1 | 2.900 TYP. | | |
| L2 | 1.400 | 1.500 | 1.600 |
| L3 | 1.800 TYP. | | |
| L4 | 0.600 | 0.800 | 1.000 |
| L5 | 0.900 | - | 1.250 |
| Φ | 1.100. | - | 1.300 |
| θ | 0° | - | 8° |
| V | 5.350 | | |